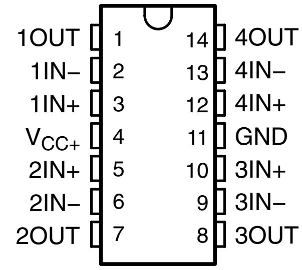
THE DATASHEET OF

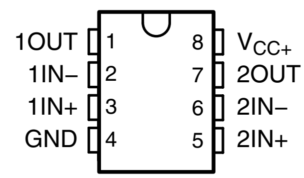
LMV324QDRQ1

- **Qualified for Automotive Applications**
- **2.7-V and 5-V Performance**
- **No Crossover Distortion**
- **Low Supply Current:**
  LMV321 . . . 130 μA Typ
  LMV358 . . . 210 μA Typ
  LMV324 . . . 410 μA Typ
- **Rail-to-Rail Output Swing**

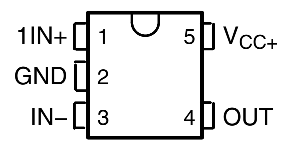
LMV324 . . . D OR PW PACKAGE
(TOP VIEW)



LMV358 . . . D OR PW PACKAGE
(TOP VIEW)



LMV321 . . . DBV PACKAGE
(TOP VIEW)



description/ordering information

The LMV321, LMV358, and LMV324 are single, dual, and quad low-voltage (2.7 V to 5.5 V) operational amplifiers with rail-to-rail output swing.

The LMV321, LMV358, and LMV324 are the most cost-effective solution for applications where low-voltage operation, space saving, and low price are required. These amplifiers were designed specifically for low-voltage (2.7 V to 5 V) operation, with performance specifications meeting or exceeding the LM358 and LM324 devices that operate from 5 V to 30 V. Additional features of the LMV3xx devices are a common-mode input voltage range that includes ground, 1-MHz unity-gain bandwidth, and 1-V/μs slew rate.

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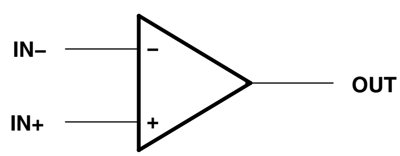
ORDERING INFORMATION†

T_A		PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	Single	SOT23-5 (DBV)	Reel of 3000	LMV321IDBVRQ1	RC1B
–40°C to 85°C	Dual	SOIC (D)	Tube of 75	LMV358IDQ1	358IQ1
			Reel of 2500	LMV358IDRQ1	
		TSSOP (PW)	Reel of 2000	LMV358IPWRQ1	358IQ1
–40°C to 85°C	Quad	SOIC (D)	Tube of 50	LMV324IDQ1	LMV324IQ1
			Reel of 2500	LMV324IDRQ1	
		TSSOP (PW)	Reel of 2000	LMV324IPWRQ1	V324IQ1
–40°C to 125°C	Single	SOT23-5 (DBV)	Reel of 3000	LMV321QDBVRQ1	RCCB
–40°C to 125°C	Dual	SOIC (D)	Tube of 75	LMV358QDQ1	V358Q1
			Reel of 2500	LMV358QDRQ1	
		TSSOP (PW)	Reel of 2000	LMV358QPWRQ1	V358Q1
–40°C to 125°C	Quad	SOIC (D)	Tube of 50	LMV324QDQ1	LMV324Q1
			Reel of 2500	LMV324QDRQ1	
		TSSOP (PW)	Reel of 2000	LMV324QPWRQ1	MV324Q1

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

‡ Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

symbol (each amplifier)



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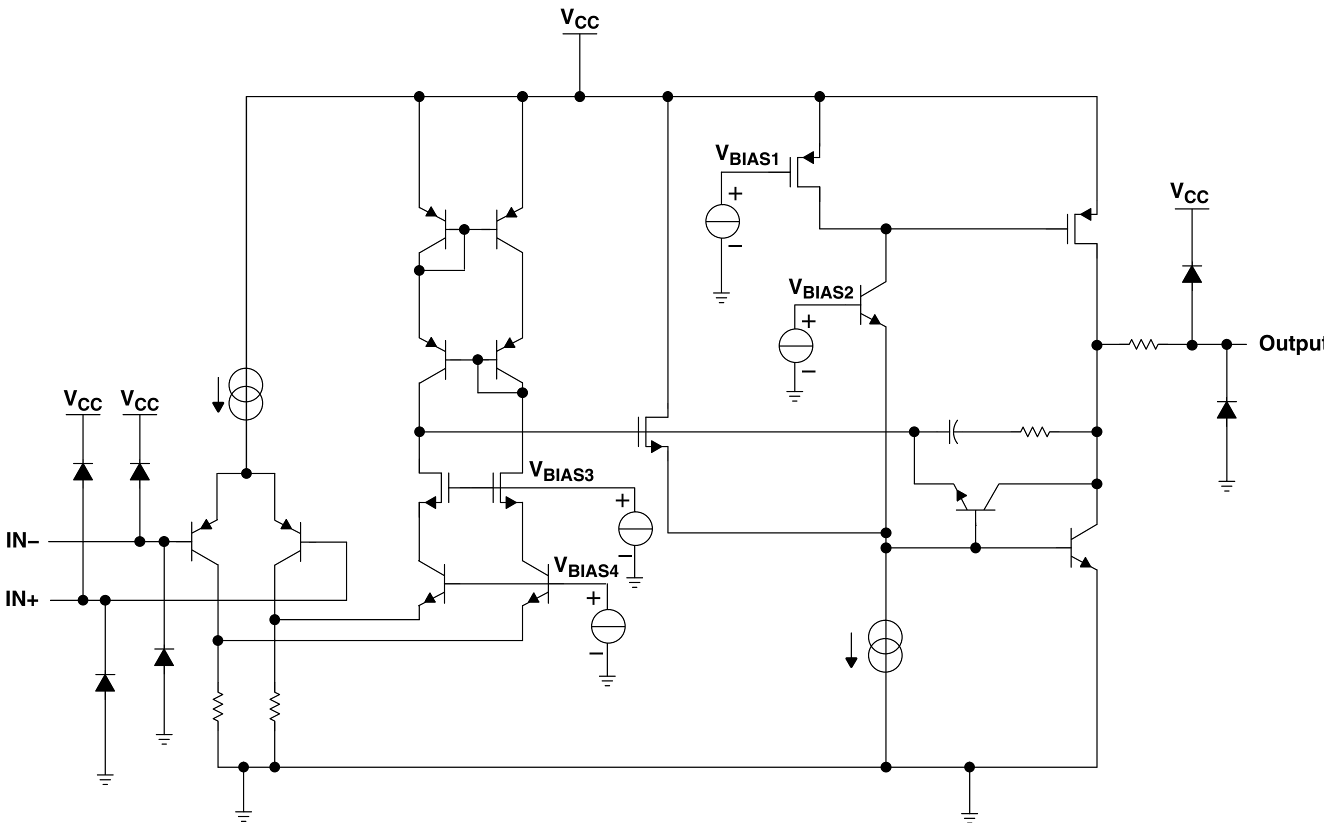
LMV324 simplified schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 5.5 V
Differential input voltage, V_{ID} (see Note 2) . . . . . ±5.5 V
Input voltage, V_I (either input) . . . . . 0 to 5.5 V
Duration of output short circuit (one amplifier) to ground at (or below) T_A = 25°C,
V_{CC} ≤ 5.5 V (see Note 3) . . . . . Unlimited
Package thermal impedance, θ_{JA} (see Notes 4 and 5): D (8-pin) package . . . . . 97°C/W
D (14-pin) package . . . . . 86°C/W
DBV (5-pin) package . . . . . 206°C/W
PW (8-pin) package . . . . . 149°C/W
PW (14-pin) package . . . . . 113°C/W
Operating virtual junction temperature, T_J . . . . . 150°C
Storage temperature range, T_{stg} . . . . . –65 to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES:
1. All voltage values (except differential voltages and V_{CC} specified for the measurement of I_{OS}) are with respect to the network GND.
2. Differential voltages are at IN+ with respect to IN–.
3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
4. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Selecting the maximum of 150°C can affect reliability.
5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 6)

			MIN	MAX	UNIT
V_{CC}	Supply voltage (single-supply operation)		2.7	5.5	V
V_{IH}	Amplifier turn-on voltage level	V_{CC} = 2.7 V	1.7		V
		V_{CC} = 5 V	3.5		
V_{IL}	Amplifier turn-off voltage level	V_{CC} = 2.7 V		0.7	V
		V_{CC} = 5 V		1.5	
T_A	Operating free-air temperature	I suffix	–40	85	°C
		Q suffix	–40	125	

NOTE 6: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics at T_A = 25°C, V_{CC+} = 2.7 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage				1.7	7	mV
$\alpha_{V_{IO}}$	Average temperature coefficient of input offset voltage				5		μV/°C
I_{IB}	Input bias current				11	250	nA
I_{IO}	Input offset current				5	50	nA
CMRR	Common-mode rejection ratio	V_{CM} = 0 to 1.7 V		50	63		dB
k_{SVR}	Supply-voltage rejection ratio	V_{CC} = 2.7 V to 5 V, V_O = 1 V		50	60		dB
V_{ICR}	Common-mode input voltage range	CMRR ≥ 50 dB		0 to 1.7	–0.2 to 1.9		V
	Output swing	R_L = 10 kΩ to 1.35 V	High level	V_{CC} – 100	V_{CC} – 10		mV
			Low level		60	180	
I_{CC}	Supply current	LMV321			80	170	μA
		LMV358 (both amplifiers)			140	340	
		LMV324 (all four amplifiers)			260	680	
B_1	Unity-gain bandwidth	C_L = 200 pF			1		MHz
ϕ_m	Phase margin				60		deg
G_m	Gain margin				10		dB
V_n	Equivalent input noise voltage	f = 1 kHz			46		nV/√Hz
I_n	Equivalent input noise current	f = 1 kHz			0.17		pA/√Hz

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electrical characteristics at specified free-air temperature range, V_{CC+} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A†	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage			25°C		1.7	7	mV
				Full range			9	
$\alpha_{V_{IO}}$	Average temperature coefficient of input offset voltage			25°C		5		μV/°C
I_{IB}	Input bias current			25°C		15	250	nA
				Full range			500	
I_{IO}	Input offset current			25°C		5	50	nA
				Full range			150	
CMRR	Common-mode rejection ratio	V_{CM} = 0 to 4 V		25°C	50	65		dB
k_{SVR}	Supply-voltage rejection ratio	V_{CC} = 2.7 V to 5 V, V_O = 1 V, V_{CM} = 1 V		25°C	50	60		dB
V_{ICR}	Common-mode input voltage range	CMMR ≥ 50 dB		25°C	0 to 4	–0.2 to 4.2		V
	Output swing	R_L = 2 kΩ to 2.5 V	High level	25°C	V_{CC} – 300	V_{CC} – 40		mV
				Full range	V_{CC} – 400			
			Low level	25°C		120	300	
				Full range			400	
		R_L = 10 kΩ to 2.5 V	High level	25°C	V_{CC} – 100	V_{CC} – 10		
				Full range	V_{CC} – 200			
			Low level	25°C		65	180	
				Full range			280	
A_{VD}	Large-signal differential voltage gain	R_L = 2 kΩ		25°C	15	100		V/mV
				Full range	10			
I_{OS}	Output short-circuit current	Sourcing, V_O = 0 V		25°C	5	60		mA
		Sinking, V_O = 5 V			10	160		
I_{CC}	Supply current	LMV321		25°C		130	250	μA
				Full range			350	
		LMV358 (both amplifiers)		25°C		210	440	
				Full range			615	
		LMV324 (all four amplifiers)		25°C		410	830	
				Full range			1160	
B_1	Unity-gain bandwidth	C_L = 200 pF		25°C		1		MHz
ϕ_m	Phase margin			25°C		60		deg
G_m	Gain margin			25°C		10		dB
V_n	Equivalent input noise voltage	f = 1 kHz		25°C		39		nV/√Hz
I_n	Equivalent input noise current	f = 1 kHz		25°C		0.21		pA/√Hz
SR	Slew rate			25°C		1		V/μs

† Full range is –40°C to 85°C for I-level part, –40°C to 125°C for Q-level part.

TYPICAL CHARACTERISTICS

GAIN AND PHASE MARGIN vs FREQUENCY

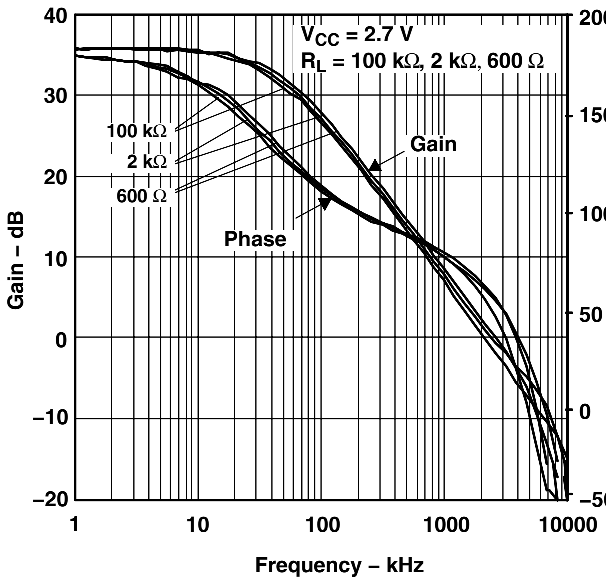

Figure 1

GAIN AND PHASE MARGIN vs FREQUENCY

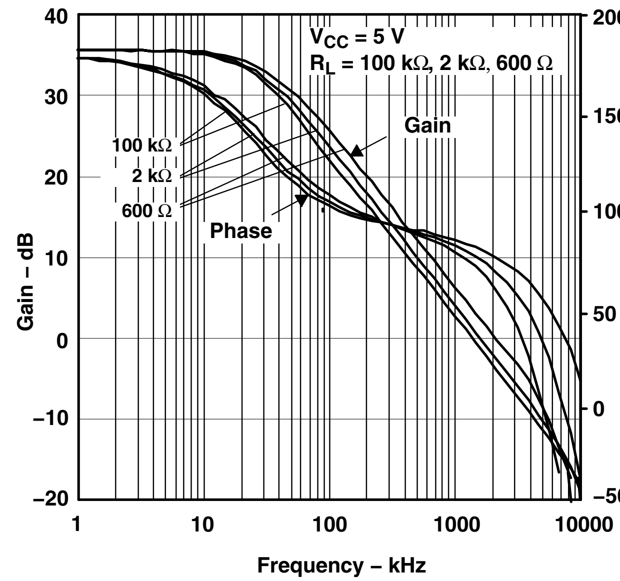

Figure 2

GAIN AND PHASE MARGIN vs FREQUENCY

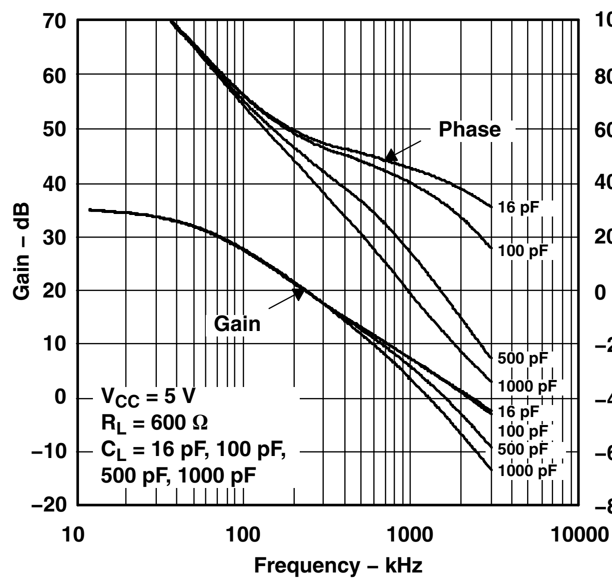

Figure 3

GAIN AND PHASE MARGIN vs FREQUENCY

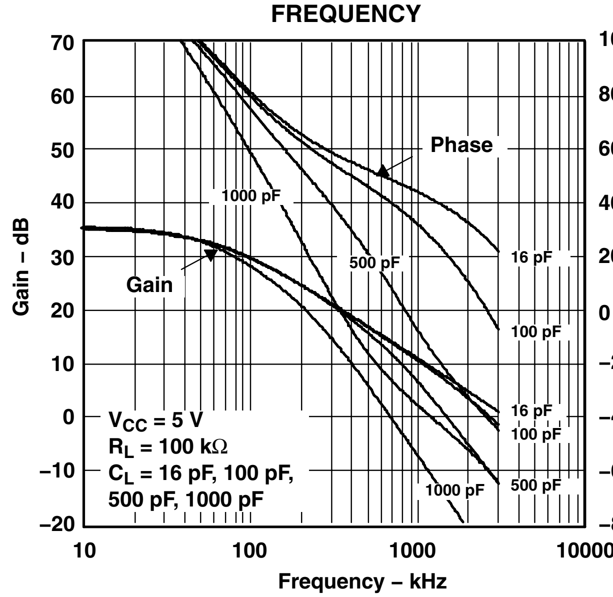

Figure 4

TYPICAL CHARACTERISTICS

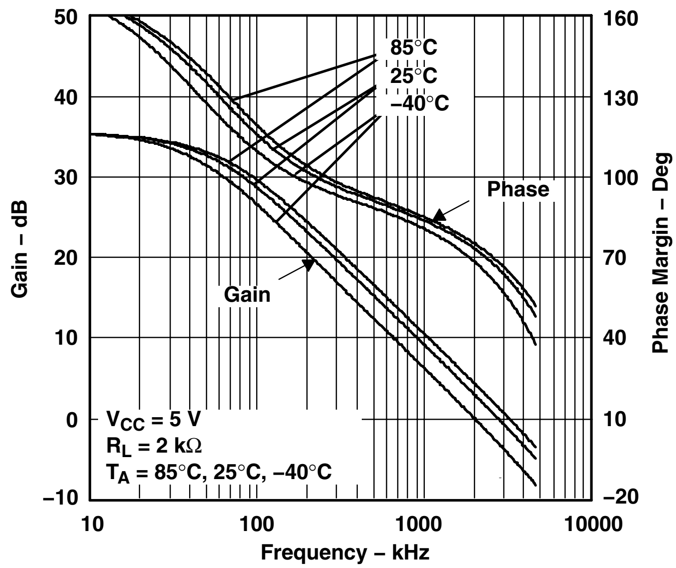

Figure 5

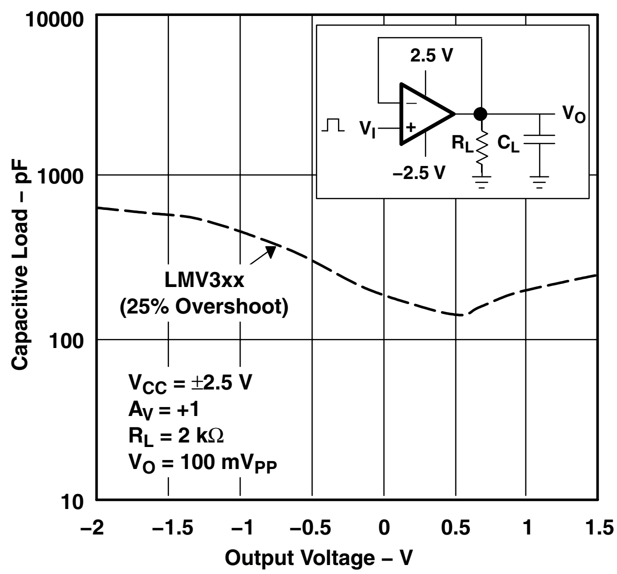

Figure 6

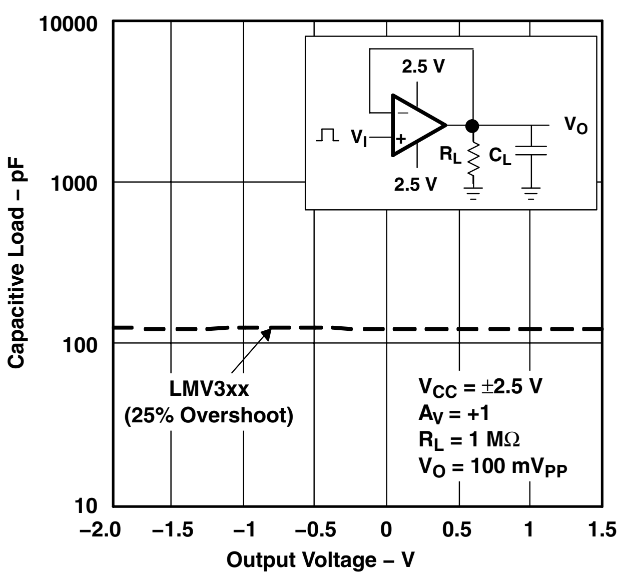

Figure 7

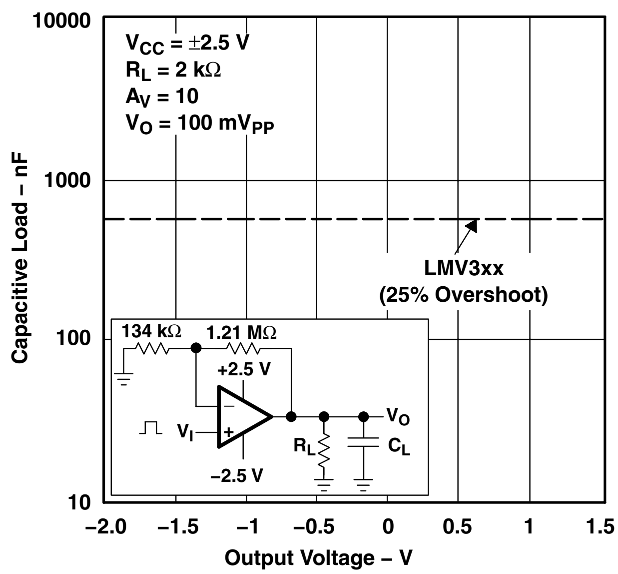

Figure 8

TYPICAL CHARACTERISTICS

STABILITY vs CAPACITIVE LOAD

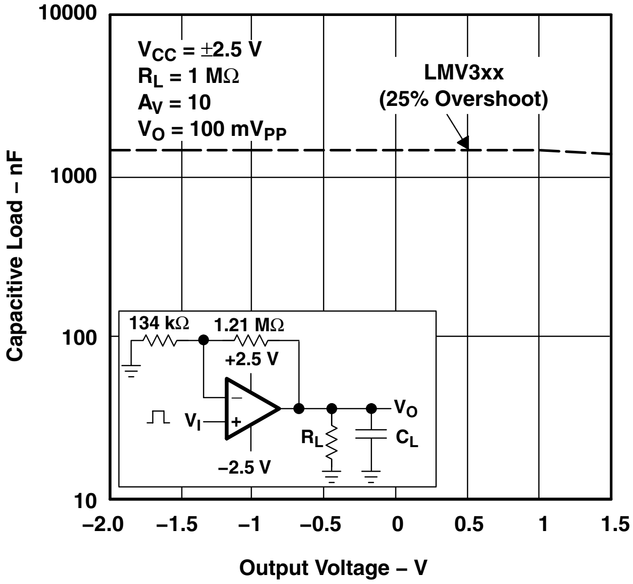

Figure 9

SLEW RATE vs SUPPLY VOLTAGE

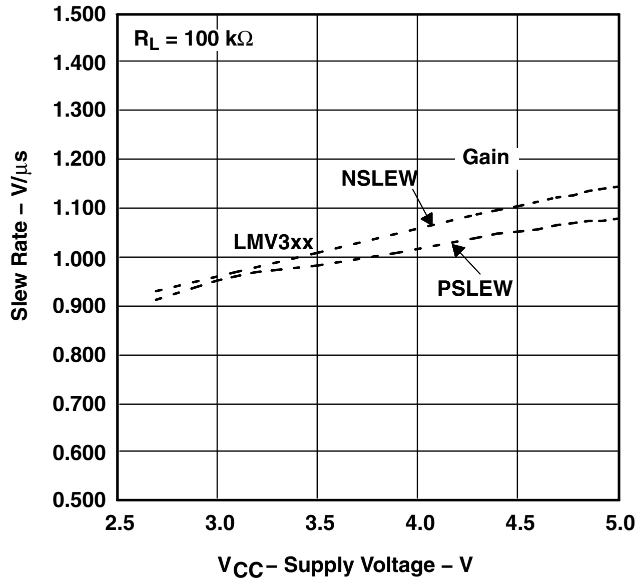

Figure 10

SUPPLY CURRENT vs SUPPLY VOLTAGE – QUAD AMPLIFIER

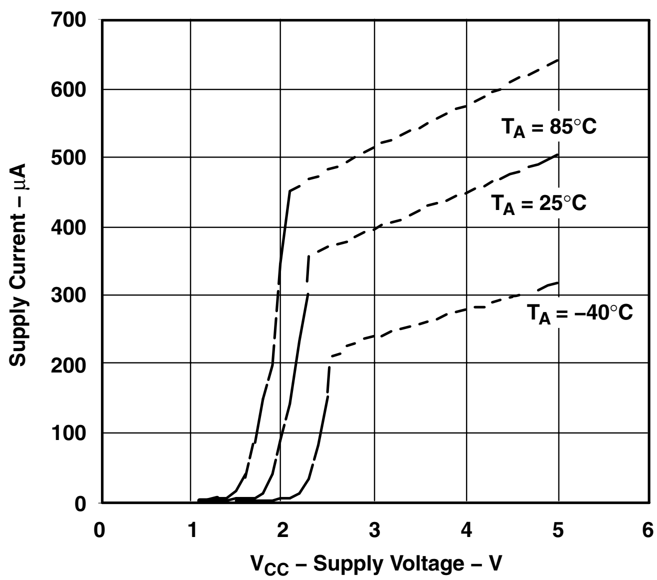

Figure 11

INPUT CURRENT vs TEMPERATURE

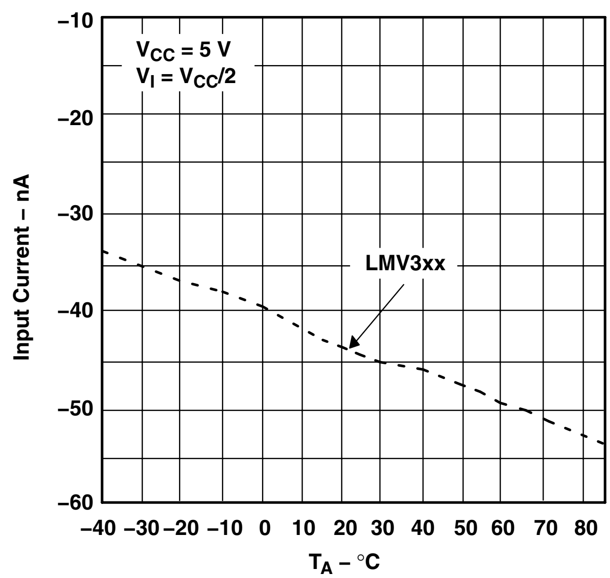

Figure 12

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TYPICAL CHARACTERISTICS

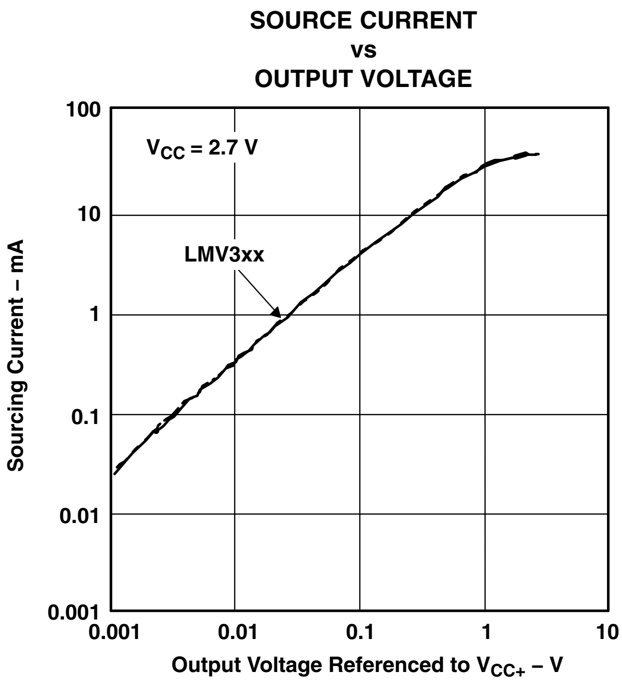

Figure 13

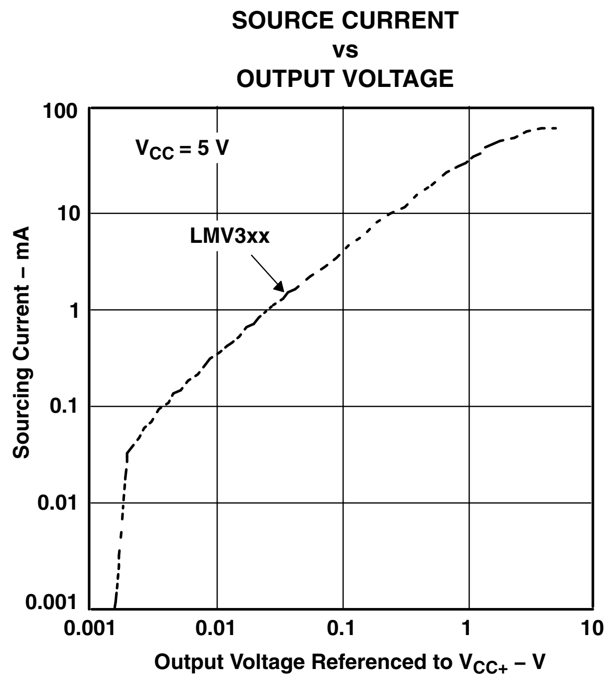

Figure 14

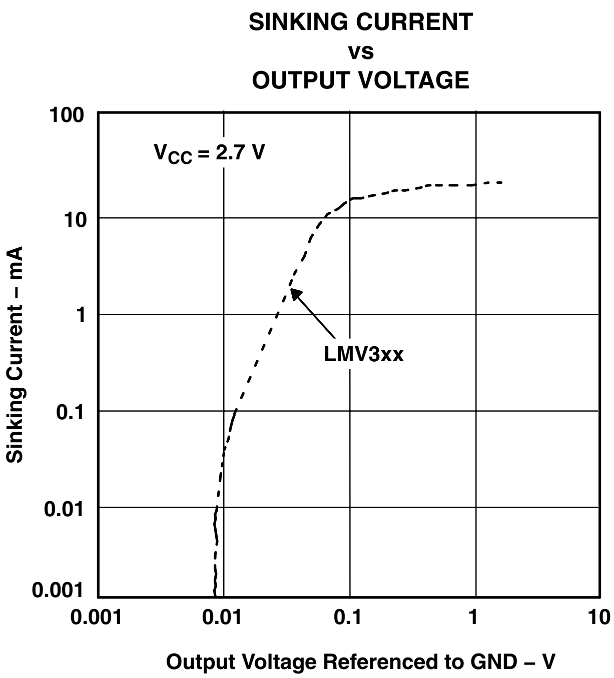

Figure 15

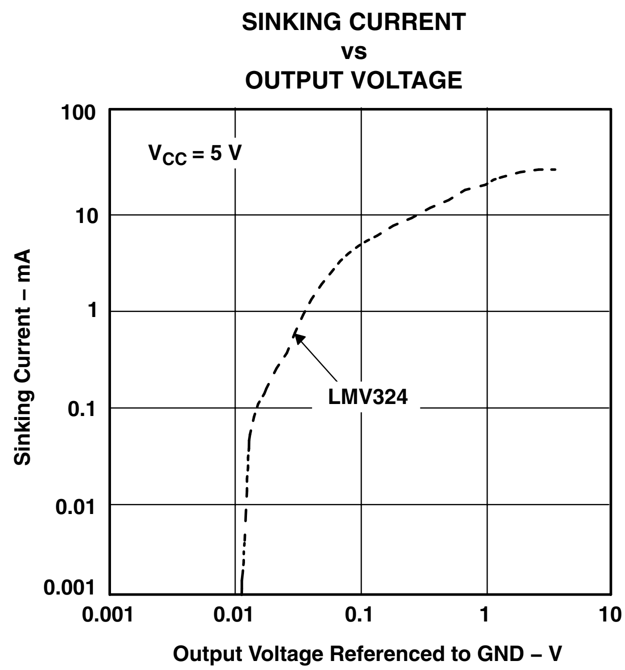

Figure 16

TYPICAL CHARACTERISTICS

SHORT-CIRCUIT CURRENT vs TEMPERATURE

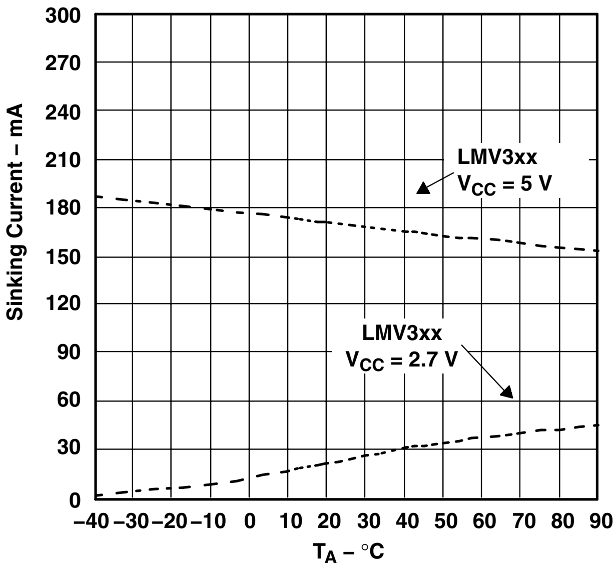

Figure 17

SHORT-CIRCUIT CURRENT vs TEMPERATURE

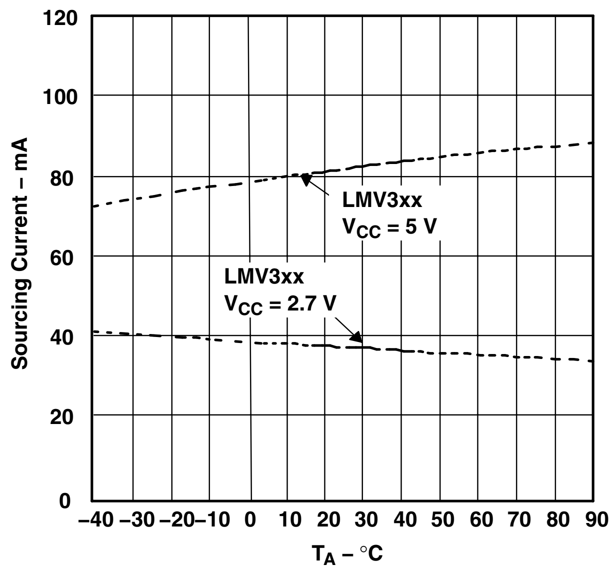

Figure 18

$-k_{SVR}$ vs FREQUENCY

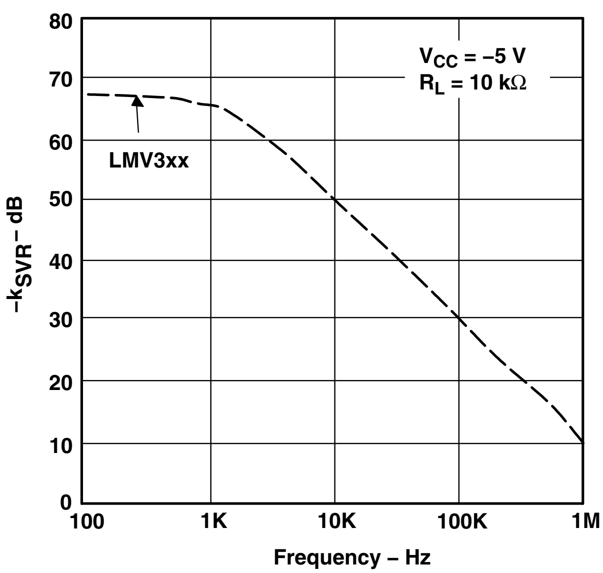

Figure 19

$+k_{SVR}$ vs FREQUENCY

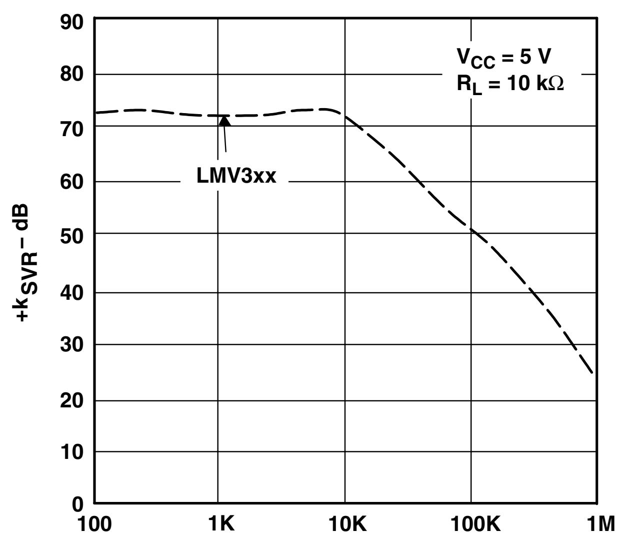

Figure 20

TYPICAL CHARACTERISTICS

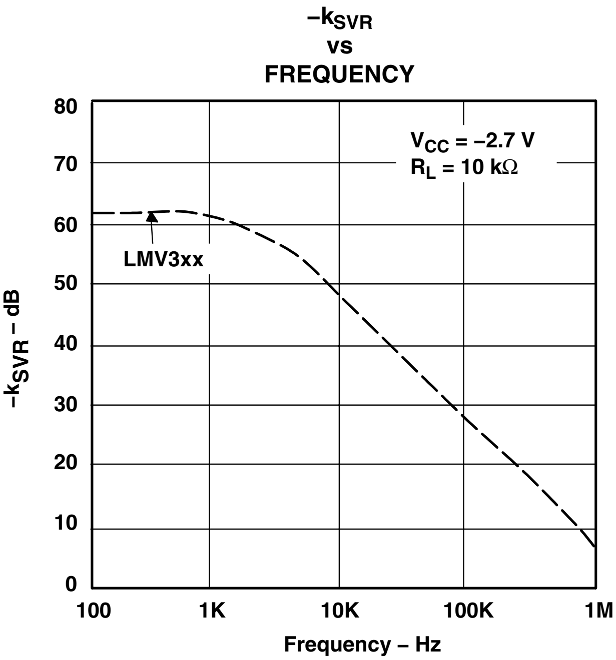

Figure 21

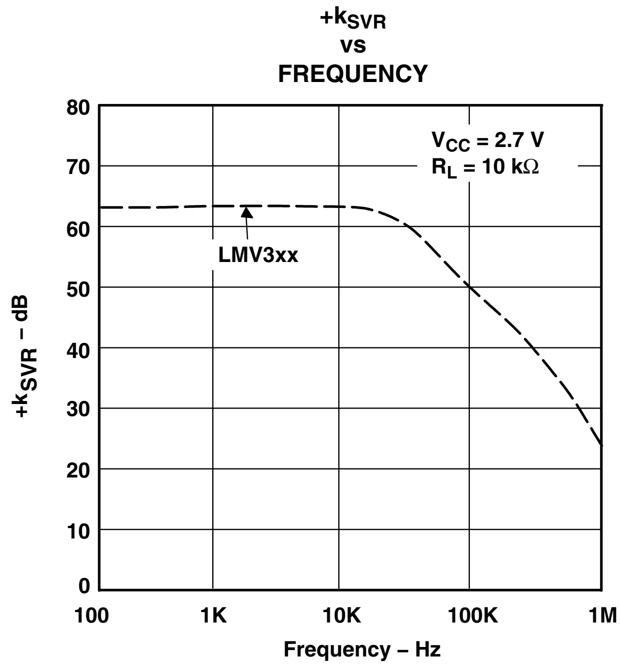

Figure 22

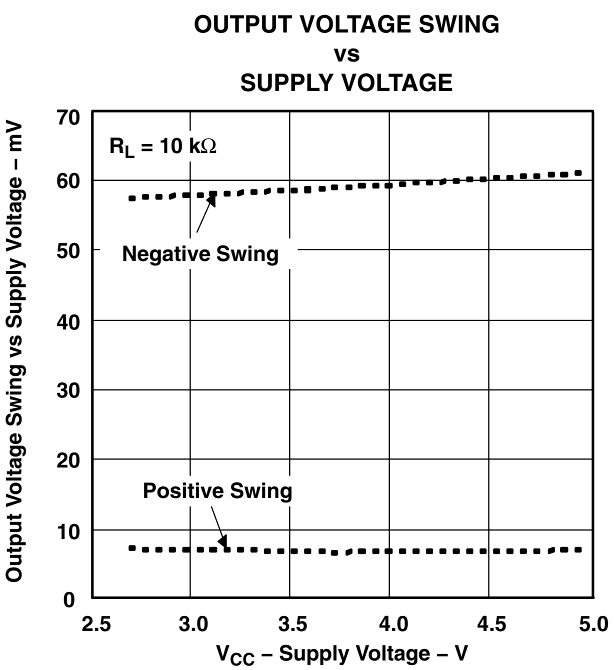

Figure 23

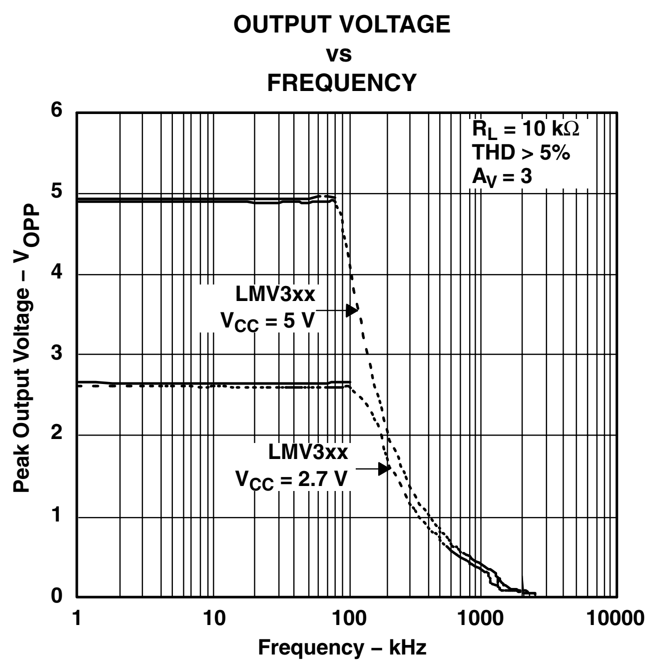

Figure 24

TYPICAL CHARACTERISTICS

OPEN-LOOP OUTPUT IMPEDANCE vs FREQUENCY

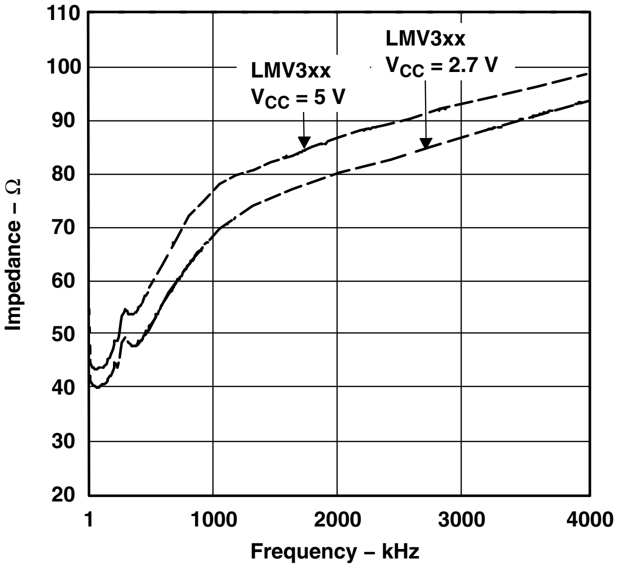

Figure 25

CROSSTALK REJECTION vs FREQUENCY

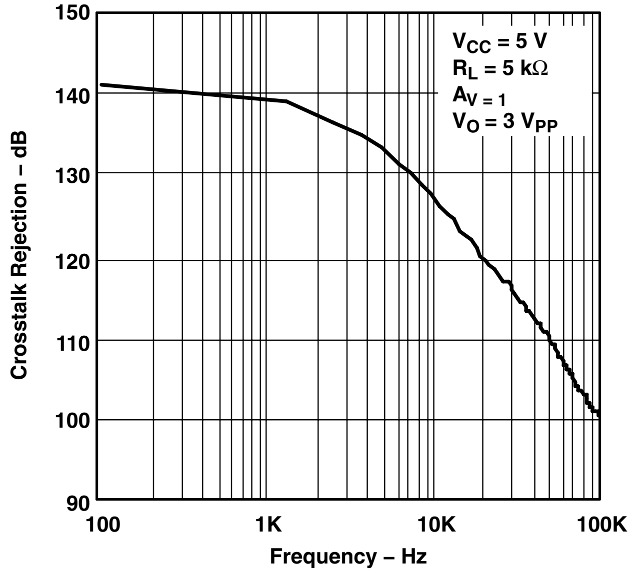

Figure 26

TYPICAL CHARACTERISTICS

NONINVERTING LARGE-SIGNAL PULSE RESPONSE

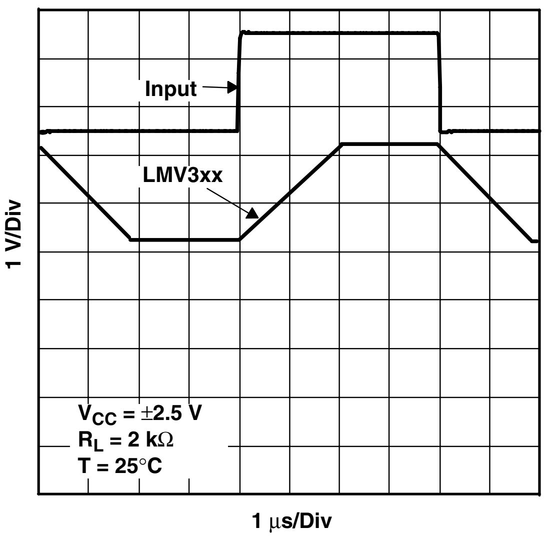

Figure 27

NONINVERTING LARGE-SIGNAL PULSE RESPONSE

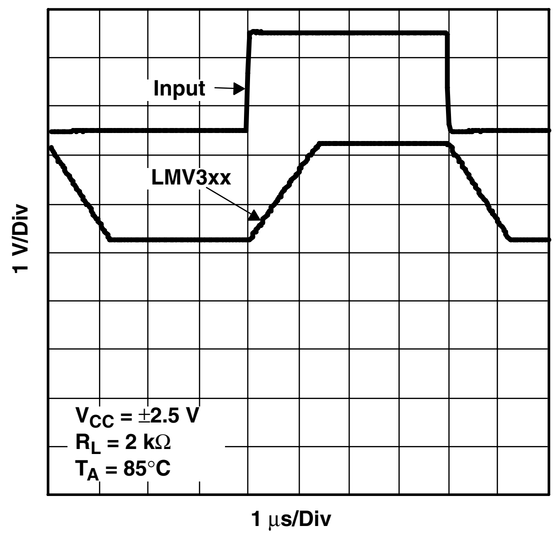

Figure 28

NONINVERTING LARGE-SIGNAL PULSE RESPONSE

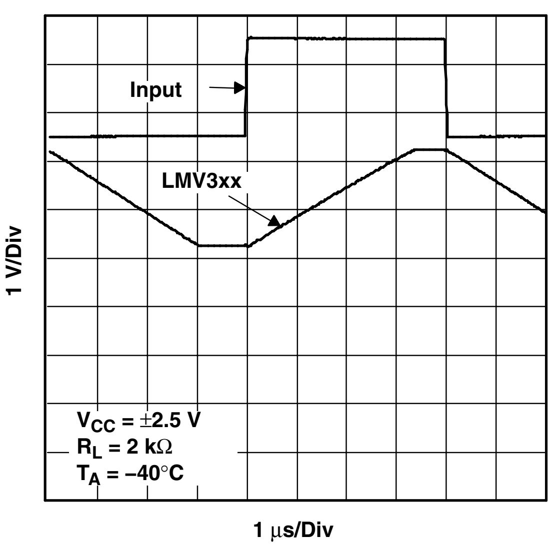

Figure 29

TYPICAL CHARACTERISTICS

NONINVERTING SMALL-SIGNAL PULSE RESPONSE

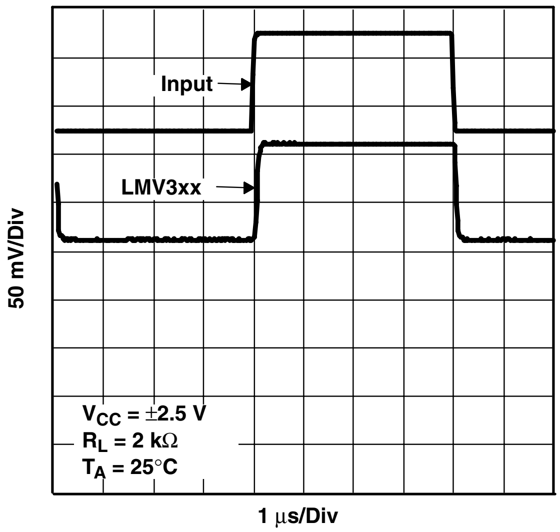

Figure 30

NONINVERTING SMALL-SIGNAL PULSE RESPONSE

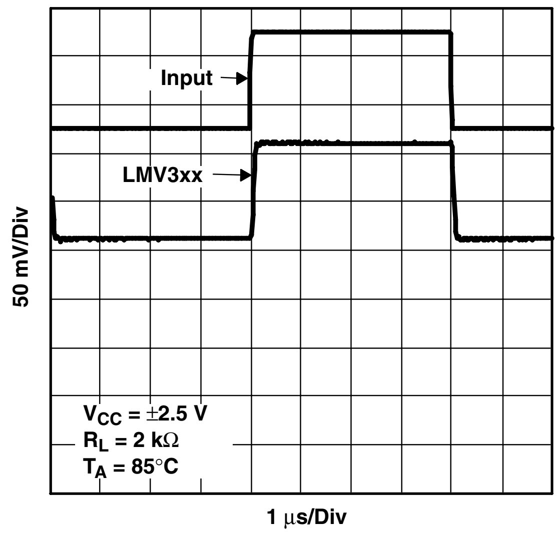

Figure 31

NONINVERTING SMALL-SIGNAL PULSE RESPONSE

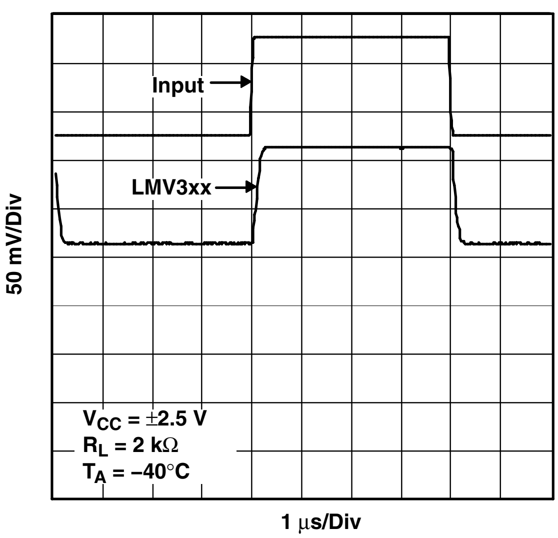

Figure 32

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TYPICAL CHARACTERISTICS

INVERTING LARGE-SIGNAL PULSE RESPONSE

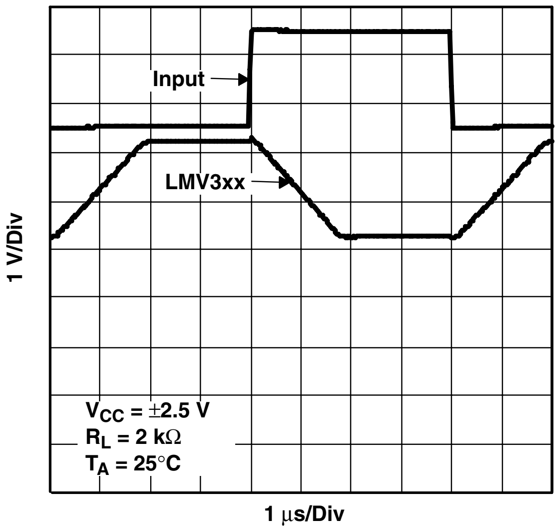

Figure 33

INVERTING LARGE-SIGNAL PULSE RESPONSE

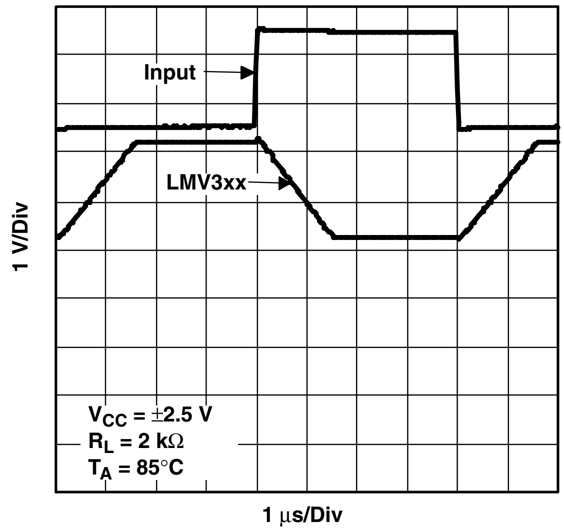

Figure 34

INVERTING LARGE-SIGNAL PULSE RESPONSE

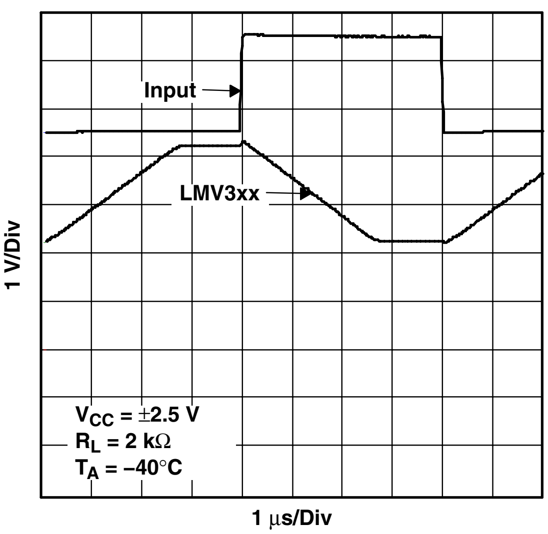

Figure 35

TYPICAL CHARACTERISTICS

INVERTING SMALL-SIGNAL PULSE RESPONSE

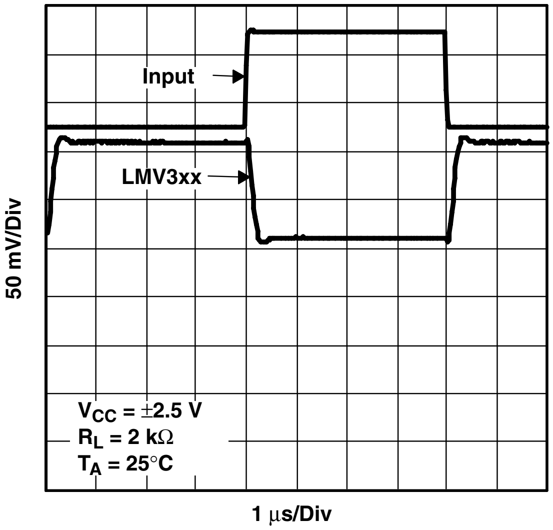

Figure 36

INVERTING SMALL-SIGNAL PULSE RESPONSE

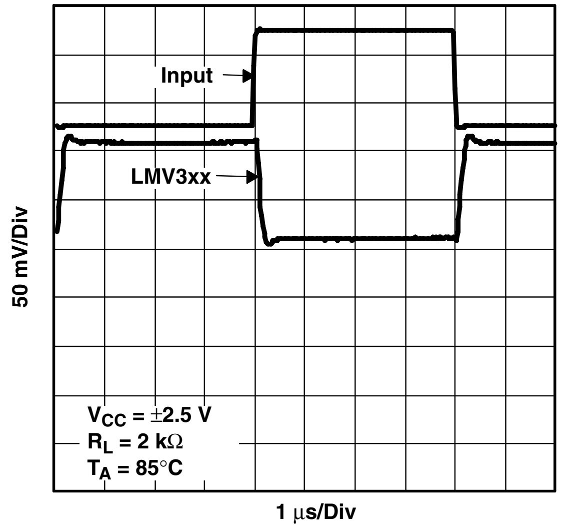

Figure 37

INVERTING SMALL-SIGNAL PULSE RESPONSE

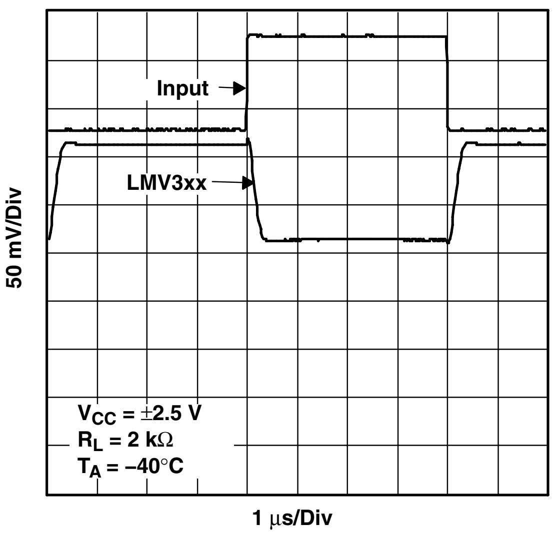

Figure 38

TYPICAL CHARACTERISTICS

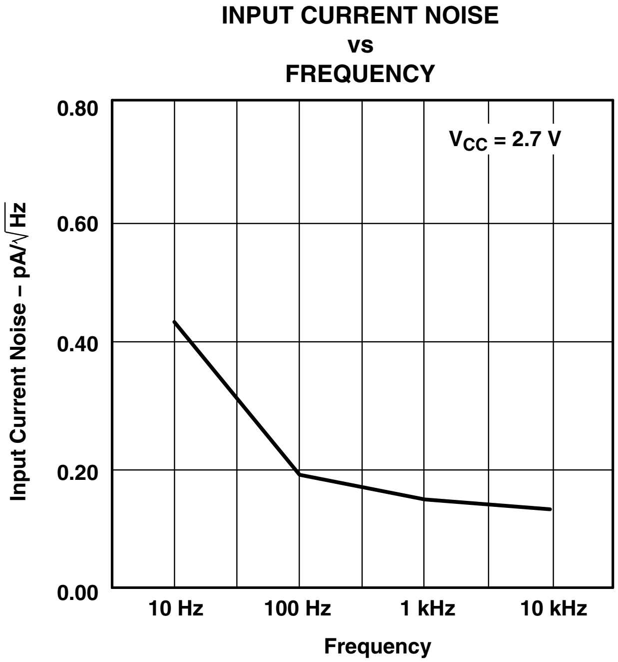

Figure 39

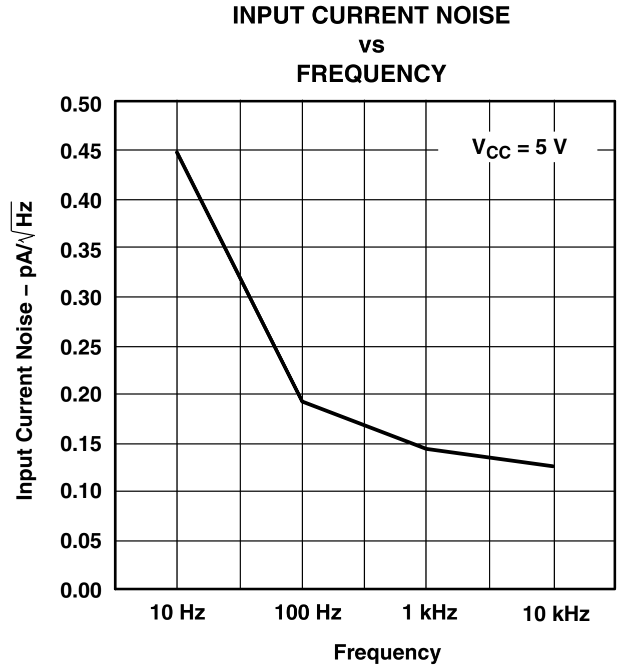

Figure 40

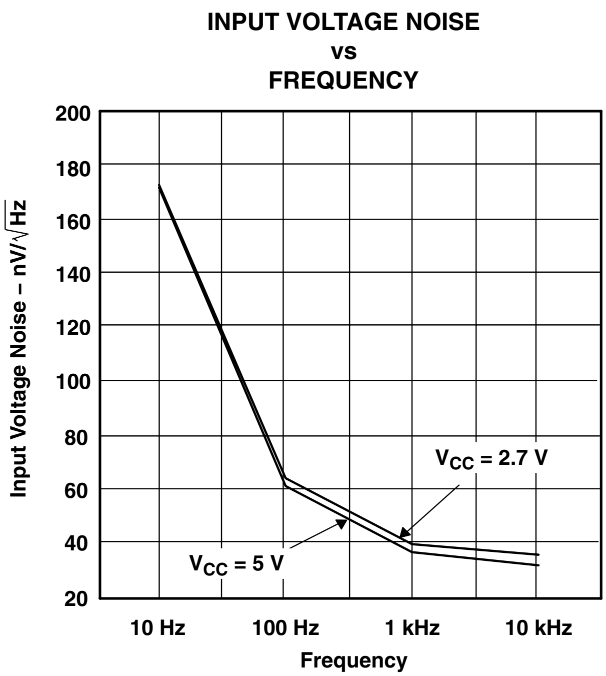

Figure 41

TYPICAL CHARACTERISTICS

THD + N vs FREQUENCY

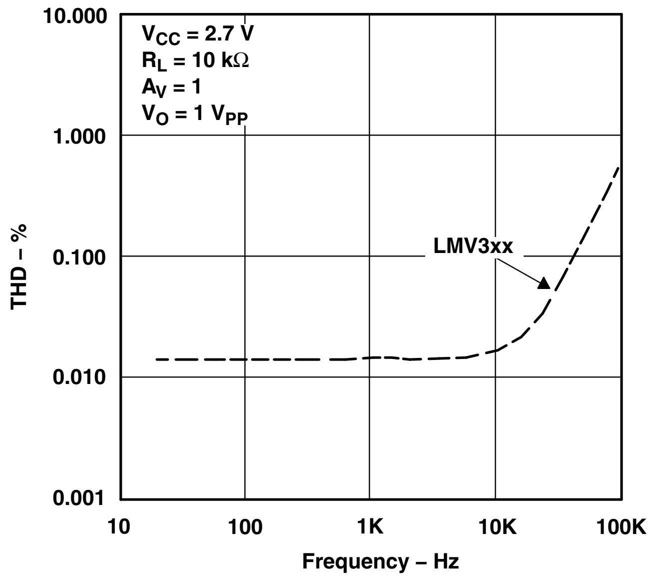

Figure 42

THD + N vs FREQUENCY

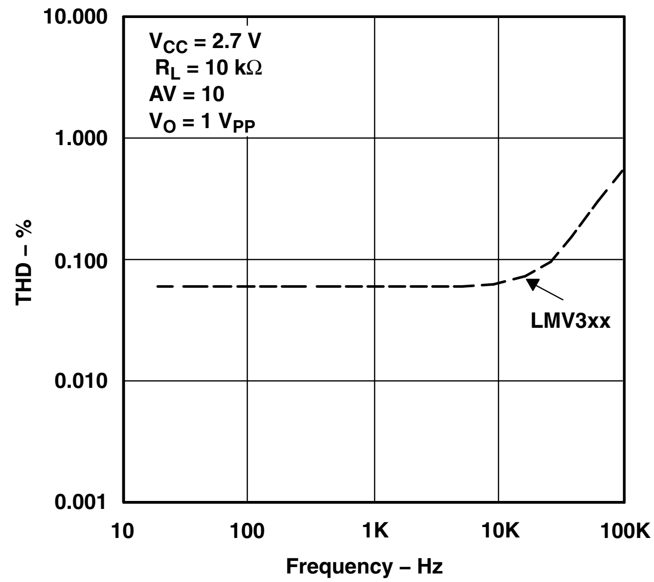

Figure 43

THD + N vs FREQUENCY

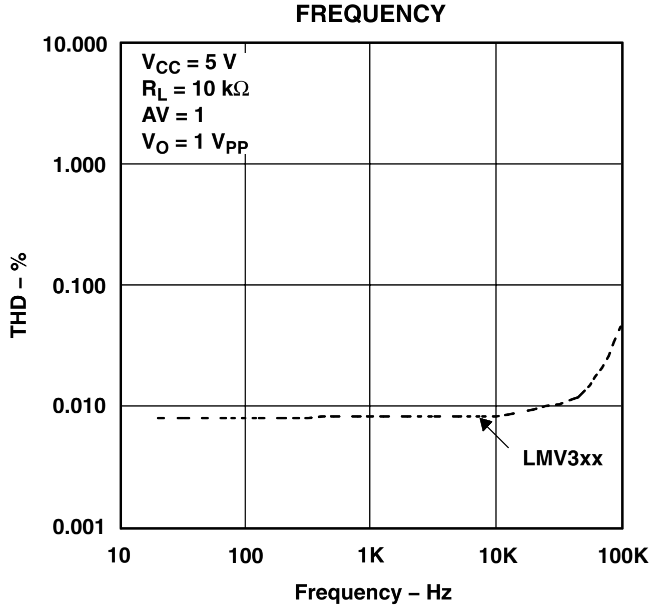

Figure 44

THD + N vs FREQUENCY

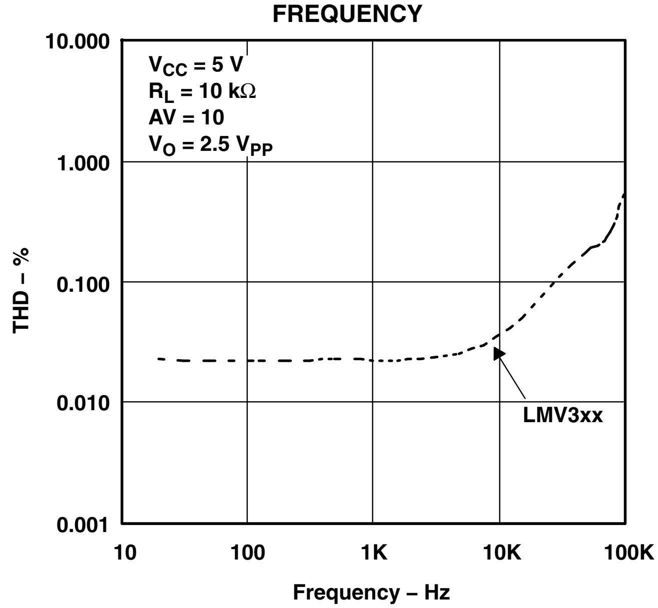

Figure 45

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LMV324QDQ1	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 125		
LMV358QDQ1	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 125		
LMV358QPWQ1	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	-40 to 125		

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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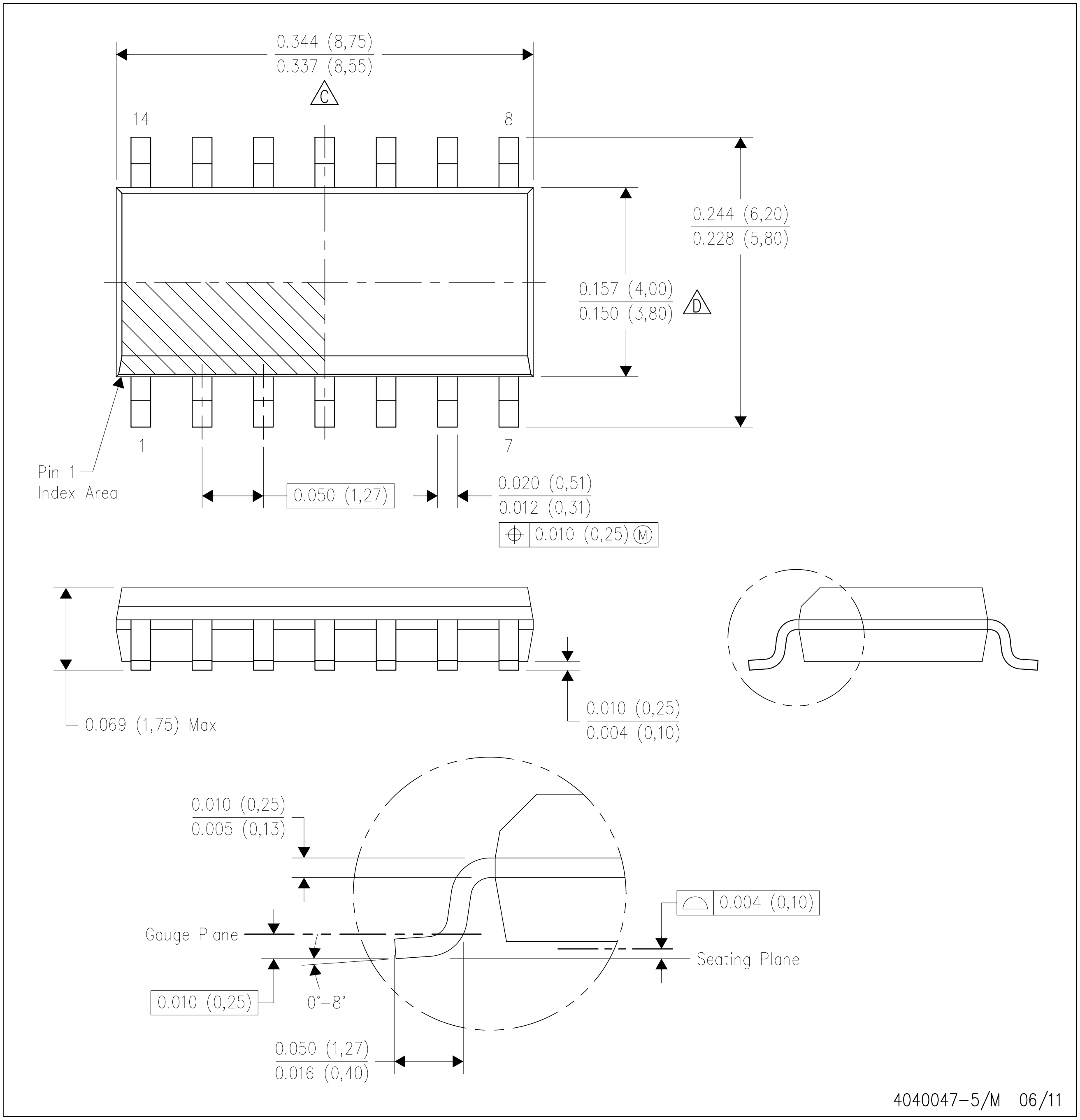
OTHER QUALIFIED VERSIONS OF LMV324-Q1, LMV358-Q1 :

- Catalog: LMV324, LMV358

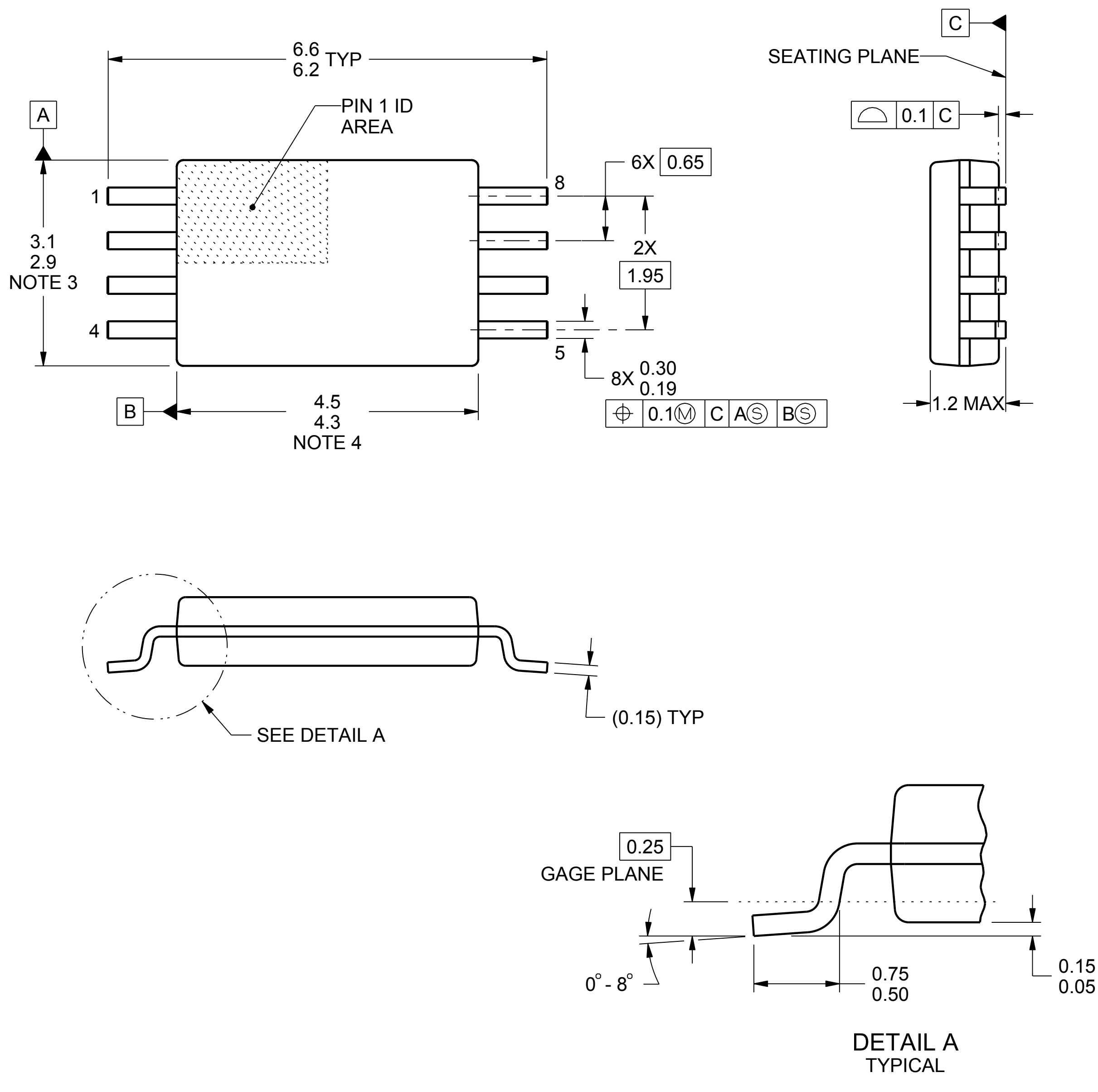
NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS-012 variation AB.



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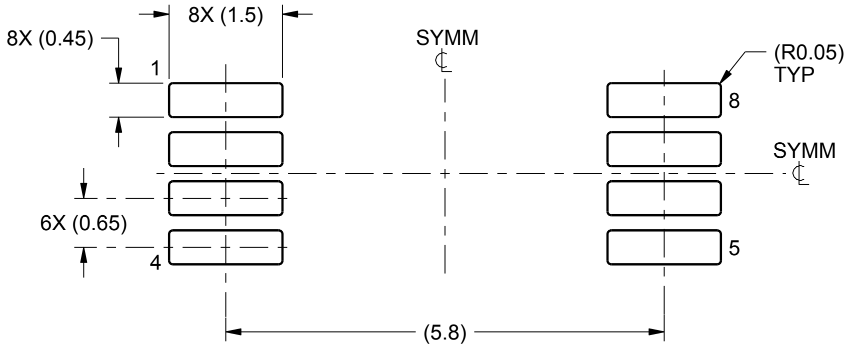
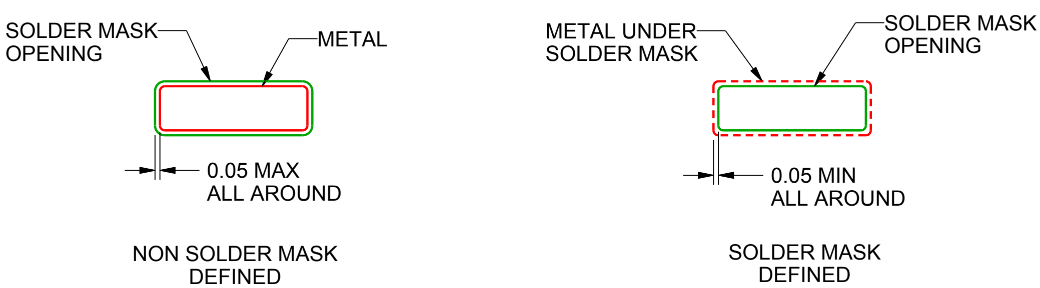
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

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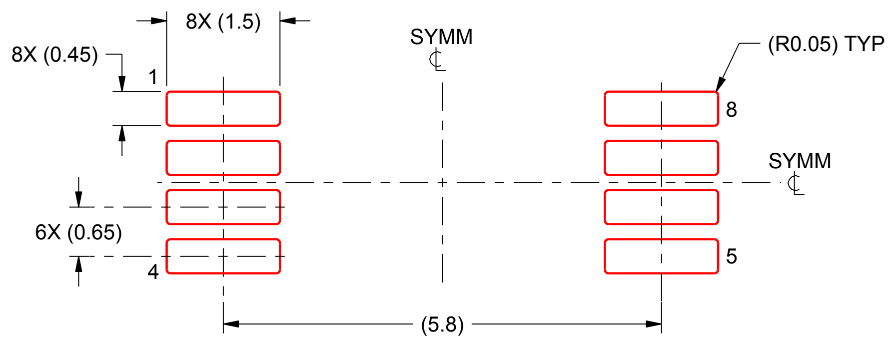
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

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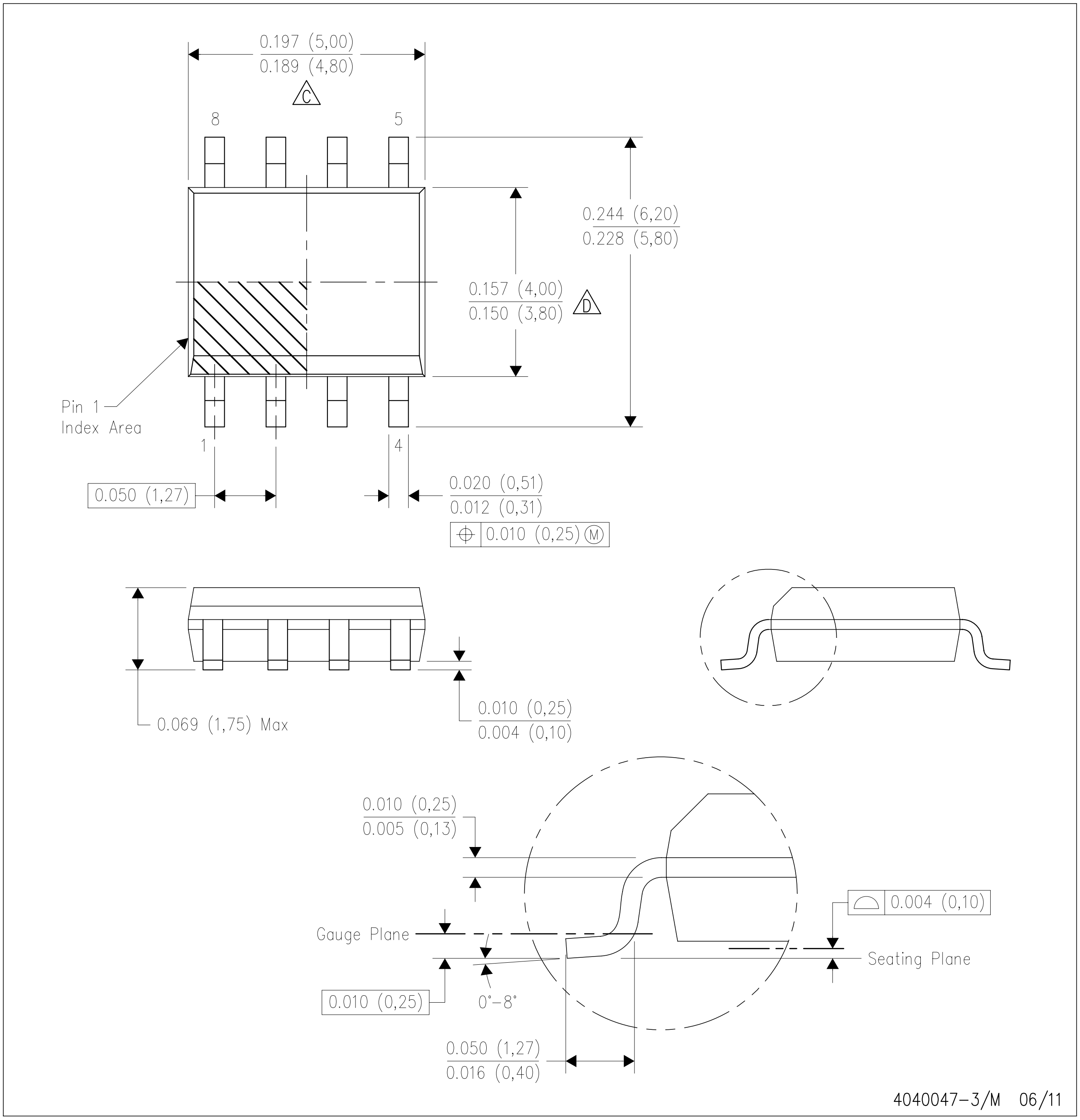
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G8) PLASTIC SMALL OUTLINE



NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

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